

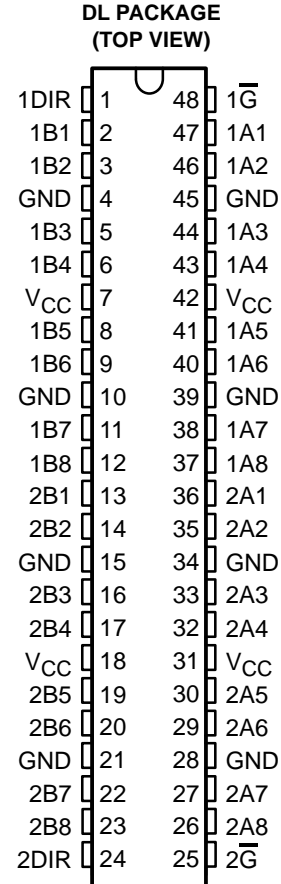
- **Controlled Baseline**
  - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –40°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree†**
- **Member of the Texas Instruments Widebus™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V<sub>CC</sub> and GND Pins Minimize High-Speed Switching Noise**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, highly accelerated stress test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life.

**description**

The SN74ACT16245Q-EP is a 16-bit bus transceiver organized as dual-octal noninverting 3-state transceivers and designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The enable ( $\overline{G}$ ) input can be used to disable the devices so that the buses are effectively isolated.



**ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SSOP – DL Tape and reel	SN74ACT16245QDLREP	ACT16245QEP

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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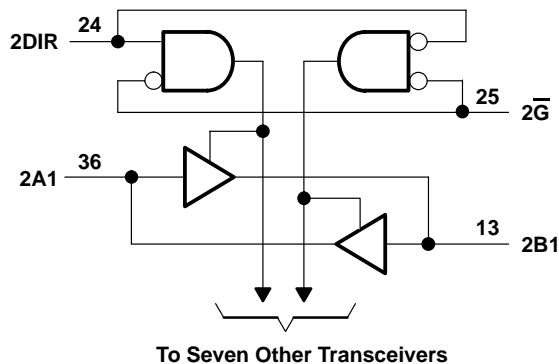
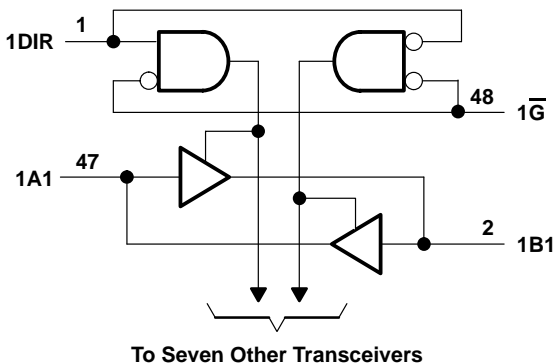
# SN74ACT16245Q-EP 16-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCAS677A – MAY 2002 – REVISED JULY 2002

FUNCTION TABLE  
(each section)

CONTROL INPUTS		OPERATION
$\overline{G}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 24$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 24$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 260$ mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DL package .....	1.2 W
Storage temperature range, $T_{stg}$ .....	$-65^\circ\text{C}$ to $150^\circ\text{C}$

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of  $150^\circ\text{C}$  and a board trace length of 750 mils.

**recommended operating conditions (see Note 3)**

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage (see Note 4)	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current		-16	mA
I <sub>OL</sub>	Low-level output current		16	mA
Δt/Δv	Input transition rise or fall rate	0	10	ns/V
T <sub>A</sub>	Operating free-air temperature	-40	125	°C

- NOTES: 3. Unused inputs should be tied to V<sub>CC</sub> through a pullup resistor of approximately 5 kΩ or greater to keep them from floating. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
4. All V<sub>CC</sub> and GND pins must be connected to the proper-voltage power supply.

**SN74ACT16245Q-EP**  
**16-BIT BUS TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**

SCAS677A – MAY 2002 – REVISED JULY 2002

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			MIN	MAX	UNIT	
			MIN	TYP	MAX				
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	4.5 V	4.4			4.4		V	
		5.5 V	5.4			5.4			
	I <sub>OH</sub> = -16 mA	4.5 V	3.94			3.94			
		5.5 V	4.94			4.94			
	I <sub>OH</sub> = -24 mA†	5.5 V				3.85			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	4.5 V				0.1		V	
		5.5 V				0.1			
	I <sub>OL</sub> = 16 mA	4.5 V				0.36			
		5.5 V				0.36			
	I <sub>OL</sub> = 24 mA†	5.5 V				0.5			
I <sub>I</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V	±0.1			±1		μA
I <sub>OZ</sub>	A or B ports‡	V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V	±0.5			±10		μA
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V	8			160		μA
ΔI <sub>CC</sub> §		One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V	0.9			1		mA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V	4.5					pF
C <sub>io</sub>	A or B ports	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V	16					pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

‡ For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current I<sub>I</sub>.

§ This is the increase in supply current for each input that is at one of the specified TTL-voltage levels rather than 0 V or V<sub>CC</sub>.

**switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)**

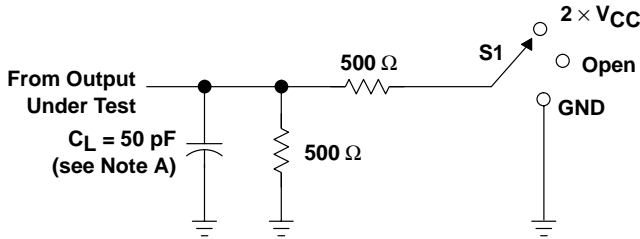
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A or B	B or A	3.2	6.9	9.3	3.2	11.5	ns
t <sub>PHL</sub>			2.6	6.4	9.2	2.6	11.1	
t <sub>PZH</sub>	G̅	B or A	2.7	6.4	9.1	2.7	10.9	ns
t <sub>PZL</sub>			3.4	7.4	10.5	3.4	12.6	
t <sub>PHZ</sub>	G̅	B or A	5.8	9.2	11.6	5.8	13.4	ns
t <sub>PLZ</sub>			5.5	8.5	10.8	5.5	12.7	

**operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C**

PARAMETER		TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per transceiver	C <sub>L</sub> = 50 pF, f = 1 MHz	52	pF
			10	

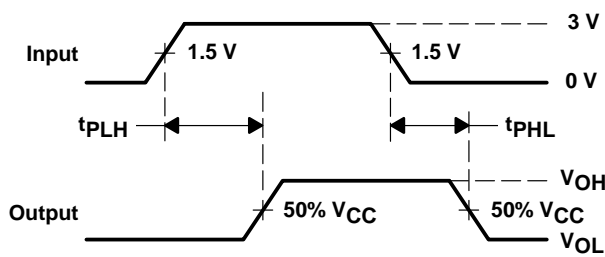


**PARAMETER MEASUREMENT INFORMATION**

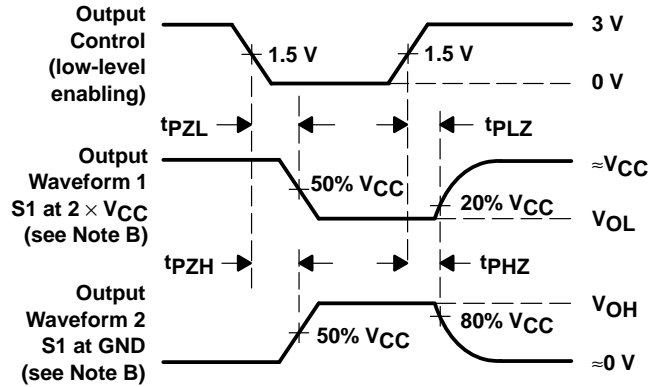


**LOAD CIRCUIT**

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	2 $\times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



**VOLTAGE WAVEFORMS**



**VOLTAGE WAVEFORMS**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .  
 D. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ACT16245QDLREP	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03601-01XE	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT16245QDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

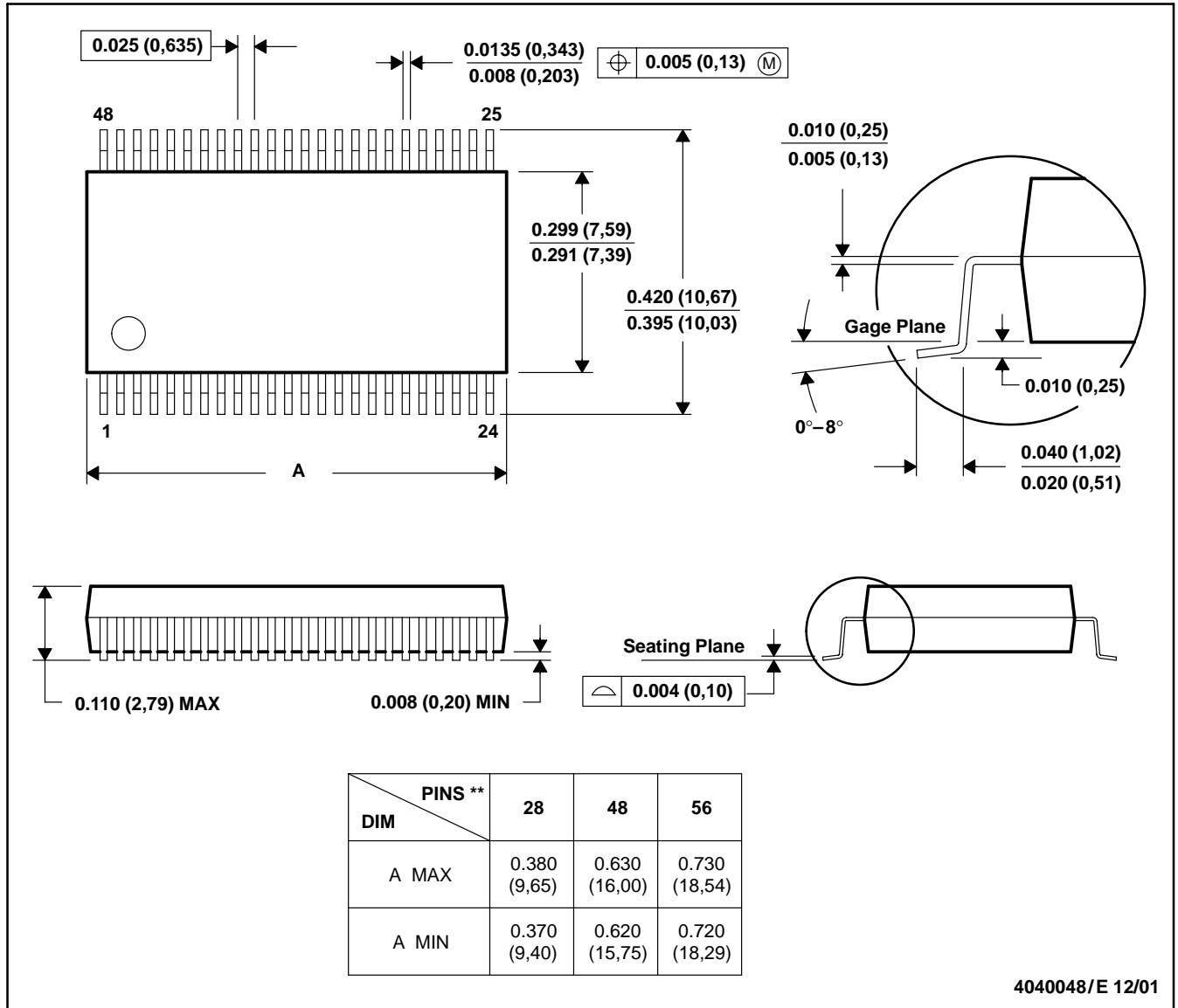
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT16245QDLREP	SSOP	DL	48	1000	346.0	346.0	49.0



DL (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MO-118

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ACT16245QDLREP	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	ACT16245QEP	<a href="#">Samples</a>
V62/03601-01XE	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	ACT16245QEP	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

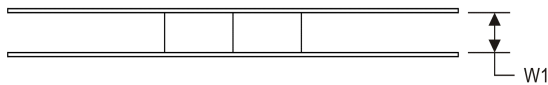
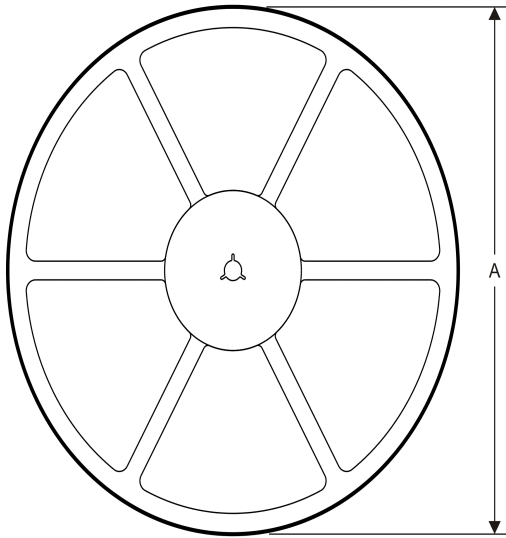
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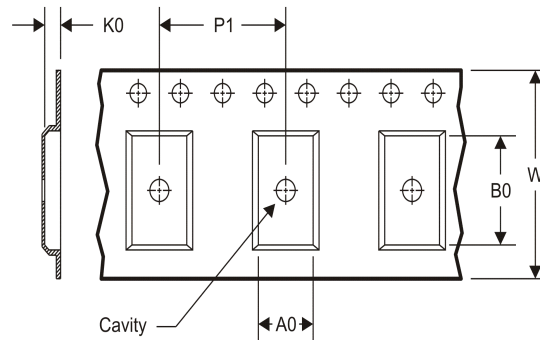
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**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**



**TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT16245QDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT16245QDLREP	SSOP	DL	48	1000	367.0	367.0	55.0

# MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MO-118

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